



Please amend the application as follows:

**In the Claims:**

✓  
Please cancel non-elected Claims 22-28 without prejudice.

Please add the following new claims:

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29. (new) A packaged integrated circuit, comprising:

A<sup>1</sup>  
a substrate including an insulating material and a conductive material disposed over the insulating material, the conductive material comprising a plurality of contacts, the conductive material further comprising a conductive ring disposed around the periphery of said plurality of contacts.

30. (new) The packaged integrated circuit of Claim 29, wherein said conductive material further comprises a trace formed of said conductive material over said insulating material and connected to said conductive ring such that said trace surrounds a selected one of said plurality of contacts.

31. (new) The packaged integrated circuit of Claim 29, wherein said conductive material further comprises a trace formed of said conductive material over said insulating material and connected to said conductive ring such that said trace surrounds selected contacts in said plurality of contacts.

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**REMARKS**

Reconsideration of the above-referenced application in view of the following remarks is respectfully requested.